Customer No.: 31561
Docket No.: 11467-US-PA
Application No.: 10/605,325

REMARKS

Present Status of the Application

The Office Action has rejected claims 1-4 and 8. Specifically, claims 1 and 8 are rejected

under 35 U.S.C. 102(b) as being anticipated by Von Von Gutfeld (U. S. Patent 6,219,126).

Claim 1 is rejected under 35 U.S.C. 102(b) as being anticipated by Sakai et al. (U. S. Patent

6,222,603; hereinafter Sakai). Claims 2-4 and 8 are rejected under 35 U.S.C. 103(a) as being

unpatentable over Sakai in view of Fujimura et al. (U. S. Patent 6,151,092; hereinafter Fujimura).

Applicant has amended claims 1 and 4, and added claim 28. Applicant has cancelled claims 5-7

and 9-27, which are reserved for a divisional application, could be filed later. After entry of the

foregoing amendments, claims 1-4, 8, and 28 remain pending in the present application, and

reconsideration of those claims is respectfully requested.

Discussion of Claim Rejections under 35 USC 102

1. Claims 1 and 8 are rejected under 35 U.S.C. 102(b) as being anticipated by Von Von

Gutfeld. Claim 1 is rejected under 35 U.S.C. 102(b) as being anticipated by Sakai. Applicant

has amended claim 1. In addition, claim 28 has been added. Applicant respectfully traverses

the rejections for at least he reasons set forth below.

2. In the present invention, as for example shown in FIG. 7E and FIG. 7F, the sealant 29 can

be just formed on one of the two substrates 21 and 22 and is outside the enclosed wall 26. In

other words, the scalant is a single component as recited in amended claim 1.

3. In re Von Gutfeld, as shown in FIG 1 and FIG 2 (col. 4, lines 24-20), the scalant 2ab is

4

06/14/05 TUE-16:35 FAX 886 2 23697233

JIANQ CHYUN IPO

2006

Customer No.: 31561 Docket No.: 11467-US-PA Application No.: 10/605,325

formed from two sealing components 2a and 2b respectively on the two substrates 1a and 1b.

The sealant 2 (col. 4, lines 61-63) is also formed from two components.

Therefore, Von Gutfeld at least does not disclose the features as recited in independent

claim I and newly added claim 28.

4. In re Sakai, as for example, shown in FIG. 6, the two scalants 6 and 11 are disclosed (col.

5, line 26 - col. 6, line 51). In other words, the inner scalant 6 does not disclose the enclosed

wall of the present invention. The enclosed wall is not a scalant. Also and, Sakai does not

specifically disclose that the sealant is just formed on one of the substrate.

For at least the foregoing reasons, claim 1, 8, and 28 have distinguished over the prior art

references.

Discussion of Claim Rejections under 35 USC 103

Claims 2-4 and 8 are rejected under 35 U.S.C. 103(a) as being unpatentable over Sakai in

view of Fujimura.

With at least the same foregoing reasons applied to claim 1, Sakai does not disclose the

features as recited in independent claim 1. Fujimura also fails to disclose the missing features in

Sakai.

In re Fujimura, the sealant 11 is disposed inside the conductive wall 13.

In addition, with respect to claim 4 (see i.e. FIG 13H), Fujimura further does not disclose

5

Customer No.: 31561 Docket No.: 11467-US-PA Application No.: 10/605,325

the conductive wall 861 of the present invention.

Therefore, with at least the same foregoing reasons, claims 2-4 and 8 are patentable, wherein claim 4 is more specifically distinguishable over the prior art references.

For at least the foregoing reasons, Applicant respectfully submits that independent claim 1 patently define over the prior art references, and should be allowed. For at least the same reasons, dependent claims 2-4, 8 and 28 patently define over the prior art references as well.

Customer No.: 31561
Docket No.: 11467-US-PA
Application No.: 10/605,325

CONCLUSION

For at least the foregoing reasons, it is believed that all the pending claims 1-4, 8, and 28 of the invention patently define over the prior art and are in proper condition for allowance. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

Date: Jule 13, 2005

Belinda Lee

Registration No.: 46,863

Jianq Chyun Intellectual Property Office 7th Floor-1, No. 100 Roosevelt Road, Section 2 Taipei, 100 Taiwan

Tel: 011-886-2-2369-2800 Fax: 011-886-2-2369-7233

Email: <u>belinda@jcipgroup.com.tw</u>

<u>Usa@jcipgroup.com.tw</u>